### COF Bonding Machine

| Model | OL-1200H-SS
|-------|------------------|
| Suitability | COF Double platform Pulse heating bonding machine
| Suitable for | LCD glass and PCB, ACF attachment.
| Maintenance | Suitable for multi variety small batch production.
| Frequency | 50Hz, 1000W
| Temp Range | 50~100°C
| Indenter Qty | 4PCS
| Bonding Precision | 0.1~99.9 Seconds
| Pressure | 0.4~0.6Mpa, Dry air
| Platform Size | 220V ± 10%, 50HZ, 1000W
| Machine Capacity | 1~300" Width: 50-200mm
| N.W. | 600kg
| G.W. | 650kg
| Packing Size | 6CBM

### ACF Attach Machine

| Specification | ACF Attach M/C
|----------------|------------------|
| Model | AA005
| Suitable for | ACF attached to LCD/FPC/PSB substrate base material
| Maintenance | 0.1~99.9 Seconds, 0.1~99.9 Seconds
| Frequency | 50Hz, 1000W
| Temp Range | 50~100°C
| Indenter Qty | 4PCS
| Bonding Precision | 0.1~99.9 Seconds
| Pressure | 0.4~0.6Mpa, Dry air
| Platform Size | 220V ± 10%, 50HZ, 1000W
| Machine Capacity | 1~300" Width: 50-200mm
| N.W. | 600kg
| G.W. | 650kg
| Packing Size | 6CBM

### COG Pre-bonding Machine

| Specification | COG Pre-bonding M/C
|----------------|------------------|
| Model | OL-1285DH-SS
| Suitable for | IC bonded to the LCD which attached ACF. Used for COF repair
| Frequency | 50Hz, 1000W
| Temp Range | 50~100°C
| Indenter Qty | 4PCS
| Bonding Precision | 0.1~99.9 Seconds
| Pressure | 0.4~0.6Mpa, Dry air
| Platform Size | 220V ± 10%, 50HZ, 1000W
| Machine Capacity | 1~300" Width: 50-200mm
| N.W. | 600kg
| G.W. | 650kg
| Packing Size | 6CBM

### COF Bonding Machine

| Specification | COF Bonding Machine
|----------------|------------------|
| Model | OL-1200H-SS
| Suitable for | IC bonded to the LCD which attached ACF. Used for COF repair
| Frequency | 50Hz, 1000W
| Temp Range | 50~100°C
| Indenter Qty | 4PCS
| Bonding Precision | 0.1~99.9 Seconds
| Pressure | 0.4~0.6Mpa, Dry air
| Platform Size | 220V ± 10%, 50HZ, 1000W
| Machine Capacity | 1~300" Width: 50-200mm
| N.W. | 600kg
| G.W. | 650kg
| Packing Size | 6CBM

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**Contact Information**

Zack Wu, Mobile phone/Wechat/WhatsApp:+86 18025364779, QQ:2307972393

E-mail:2307972393@qq.com, facebook.com/szolian

<table>
<thead>
<tr>
<th>Model</th>
<th>CM006</th>
<th>CM008</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Product Name:</strong></td>
<td>1-12 inch Triple Stations Semi-Automatic High-speed COG Press</td>
<td>1-12 inch Double Stations Semi-Automatic COG bonding Machine</td>
</tr>
<tr>
<td><strong>Suitable For:</strong></td>
<td>Suitable for IC Bonded to the Panel</td>
<td>Suitable for IC Bonded to the Panel, FOR OLED panel</td>
</tr>
<tr>
<td><strong>Size Range:</strong></td>
<td>1-12 inch</td>
<td>1-12 inch</td>
</tr>
<tr>
<td><strong>C Size:</strong></td>
<td>3.2-40mm, W 0.8-3mm</td>
<td>3.2-40mm, W 0.8-3mm</td>
</tr>
<tr>
<td><strong>Machine Capacity:</strong></td>
<td>1200pcs/H</td>
<td>600pcs/H</td>
</tr>
<tr>
<td><strong>Power Supply:</strong></td>
<td>220VAC±10%, 50HZ, 2000W</td>
<td>220VAC±10%, 50HZ, 1200W</td>
</tr>
<tr>
<td><strong>Air Supply:</strong></td>
<td>0.5~0.7MPa, dry air</td>
<td>0.5~0.7MPa, dry air</td>
</tr>
<tr>
<td><strong>Platform Size:</strong></td>
<td>127*100MM</td>
<td>127*100MM</td>
</tr>
<tr>
<td><strong>Platform Precision:</strong></td>
<td>±0.01MM</td>
<td>±0.01MM</td>
</tr>
<tr>
<td><strong>Pressure Head Size:</strong></td>
<td>L45*W5MM, customizable</td>
<td>L45*W5MM, customizable</td>
</tr>
<tr>
<td><strong>Temp Range:</strong></td>
<td>RT~400℃</td>
<td>RT~400℃</td>
</tr>
<tr>
<td><strong>Time Range:</strong></td>
<td>0.1~99.9sec</td>
<td>0.1~99.9sec</td>
</tr>
<tr>
<td><strong>Product Size:</strong></td>
<td>L1025<em>W750</em>H1400MM</td>
<td>L640<em>W700</em>H1320MM</td>
</tr>
<tr>
<td><strong>Operate Height:</strong></td>
<td>830±10mm</td>
<td>800±10mm</td>
</tr>
<tr>
<td><strong>N.W.:</strong></td>
<td>About 350KG</td>
<td>About 320KG</td>
</tr>
<tr>
<td><strong>Packing Size:</strong></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

### Specification

**COG Main-Bonding Machine**

- Constant Temp Heating System
- Panasonic PLC Control system
- High precision servo motor control movement, cylinder control pressure to keep the balance between high capacity and stability
- High steel structure set, dual ceramic indenter configuration, to ensure the stability of the equipment
- Imported electrical configuration
- High quality, high successful rate.
<table>
<thead>
<tr>
<th>Model</th>
<th>Product Name</th>
<th>Suitable For</th>
<th>Specification</th>
<th>Price</th>
</tr>
</thead>
<tbody>
<tr>
<td>FP010</td>
<td>Single Head Up&amp;Down Contraposition FOG Bonding Machine</td>
<td>Stress Free with ACF Attached, press the PPC to the LCD Panel which already attached ACF</td>
<td>Constant temperature heating system + PLC Control System + Human - Machine Interface + Automatic temperature alarm + Pressure Head Level Adjustable Device + 3普80mm &amp; 4.5 inch HD LCD + Manual / automatic switching</td>
<td>0.5~0.7MPa, dry air</td>
</tr>
<tr>
<td>FC007</td>
<td>Upper and Down Contraposition movable platform</td>
<td>Suitable for alignment and press the FPC to the LCD Panel which already attached ACF</td>
<td>Constant temperature heating system + Panasonic PLC Control System + HD Colorful Upper Contraposition CCD and 10.4 inch HD LCD</td>
<td>± 0.01MM</td>
</tr>
<tr>
<td>FP008</td>
<td>Upper and Down Contraposition Pulse Bonding Machine</td>
<td>Suitable for alignment and press the FPC to the LCD Panel which already attached ACF</td>
<td>Constant temperature heating system + Panasonic PLC Control System + HD Colorful Upper Contraposition CCD and 10.4 inch HD LCD</td>
<td>± 0.015mm</td>
</tr>
<tr>
<td>FP011</td>
<td>Upper and Down Contraposition Pulse Bonding Machine</td>
<td>Suitable for alignment and press the FPC to the LCD Panel which already attached ACF</td>
<td>Constant temperature heating system + Panasonic PLC Control System + HD Colorful Upper and Down Contraposition</td>
<td>± 0.015mm</td>
</tr>
<tr>
<td>FC009</td>
<td>Upper and Down Contraposition movable platform</td>
<td>Suitable for alignment and press the FPC to the LCD Panel which already attached ACF</td>
<td>Constant temperature heating system + Panasonic PLC Control System + HD Colorful Upper and Down Contraposition</td>
<td>± 0.015mm</td>
</tr>
<tr>
<td>FP012</td>
<td>Upper and Down Contraposition Pressure Bonding Machine</td>
<td>Suitable for alignment and press the FPC to the LCD Panel which already attached ACF</td>
<td>Constant temperature heating system + Panasonic PLC Control System + HD Colorful Upper and Down Contraposition</td>
<td>± 0.015mm</td>
</tr>
<tr>
<td>No.</td>
<td>Category</td>
<td>Picture</td>
<td>Function</td>
<td>Price</td>
</tr>
<tr>
<td>-----</td>
<td>----------</td>
<td>---------</td>
<td>----------</td>
<td>-------</td>
</tr>
<tr>
<td></td>
<td>Automatic COG bonding line</td>
<td><img src="image1.png" alt="Image" /></td>
<td>Suitable for IC Bonding to the LCD, ACF attach, IC preload and the pressure completed in one time</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Automatic FOG bonding line</td>
<td><img src="image2.png" alt="Image" /></td>
<td>Suitable for FPC Bonding to the LCD, ACF Pre-press and the pressure completed in one time</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Manual IC disassembling M/C</td>
<td><img src="image3.png" alt="Image" /></td>
<td>Suitable for Disassembling 2~12inch LCD IC</td>
<td></td>
</tr>
<tr>
<td></td>
<td>High-precision press head Customized</td>
<td><img src="image4.png" alt="Image" /></td>
<td>High Precision indenters, stainless steel indenter, brass indenter, ceramic indenter, tungsten steel indenter, Pulse indenter</td>
<td></td>
</tr>
</tbody>
</table>

### Automatic COG bonding line
- **Model:** FAC001
- **Product Name:** 1~7inch Full Automatic COG bonding line
- **Suitable For:** Suitable for IC Bonding to the LCD, ACF attach, IC preload and the pressure completed in one time
- **Size Range:** 1~7 inch
- **Bonding Precision:** ±2.5UM
- **Pressure Precision:** ±5UM
- **IC Size:** L:2~40mm, W:0.8~3mm
- **Attach Qty:** 1PCS
- **Machine Capacity:** 1000pcs/H
- **Power Supply:** 220V±10%, 50HZ, 1000W
- **Air Supply:** 0.5~0.7MPa, dry air
- **Temp Range:** 1~300℃
- **Time Range:** 1~99.9sec
- **Product Size:** W1500*D2300*H1700MM
- **N.W:**
- **Packing Size:**

### Automatic FOG bonding line
- **Model:** FAF001
- **Product Name:** Automatic FOG bonding line
- **Suitable For:** Suitable for FPC Bonding to the LCD, ACF Pre-press and the pressure completed in one time
- **Size Range:** 1~7 inch
- **Pressure Precision:** ±0.005MM
- **Pressure Precision:** ±0.01MM
- **Attach Qty:** 1pcs
- **Machine Capacity:** 1000pcs/H
- **Power Supply:** 220V±10%, 50HZ, 1000W
- **Air Supply:** 0.5~0.7MPa, dry air
- **Temp Range:** 1~300℃
- **Time Range:** 1~99.9sec
- **Product Size:** W1500*D2500*H1700MM
- **N.W:**
- **Packing Size:**

### Manual IC disassembling M/C
- **Model:** ID01A
- **Product Name:** Manual IC disassembling M/C
- **Suitable For:** Suitable for Disassembling 2~12inch LCD IC
- **Heating Power:** 750W
- **Disassembly speed:** 4S/pcs
- **Power Supply:** 220V±10%, 50HZ, 200W
- **Platform Size:** 300*250MM
- **Product Size:** 400*200*500MM
- **N.W:** about 25kg
- **Packing Size:**

### High-precision press head Customized
- **Heating Power:** 1000W
- **Disassembly speed:** 100pcs/min
- **Power Supply:** 220V±10%, 50HZ, 200W
- **Platform Size:** 300*250MM
- **Product Size:** 400*200*500MM
- **N.W:** about 25kg
- **Packing Size:**

### Auxiliary Equipment & Accessories
- **Model:** ID01A
- **Product Name:** Manual IC disassembling M/C
- **Suitable For:** Suitable for Disassembling 2~12inch LCD IC
- **Heating Power:** 750W
- **Disassembly speed:** 4S/pcs
- **Power Supply:** 220V±10%, 50HZ, 200W
- **Platform Size:** 300*250MM
- **Product Size:** 400*200*500MM
- **N.W:** about 25kg
- **Packing Size:**